

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	75	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current (Note 5)	I <sub>FM</sub>	500	mA
Average Rectified Output Current (Note 5)	I <sub>O</sub>	250	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	4	A
		1	

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	200	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 10μA
Forward Voltage	V <sub>F</sub>	0.62	0.720	V	I <sub>F</sub> = 5.0mA
		—	0.855		I <sub>F</sub> = 10mA
		—	1.0		I <sub>F</sub> = 50mA
		—	1.25		I <sub>F</sub> = 150mA
Reverse Current (Note 6)	I <sub>R</sub>	—	2.5	μA	V <sub>R</sub> = 75V
			50	μA	V <sub>R</sub> = 75V, T <sub>J</sub> = 150°C
			30	μA	V <sub>R</sub> = 25V, T <sub>J</sub> = 150°C
			25	nA	V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	4.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.  
 6. Short duration pulse test used to minimize self-heating.

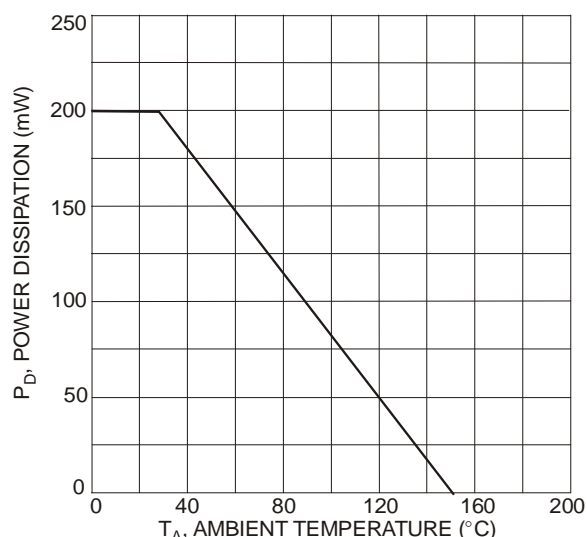


Fig. 1 Power Derating Curve, Total Package (Note 5)

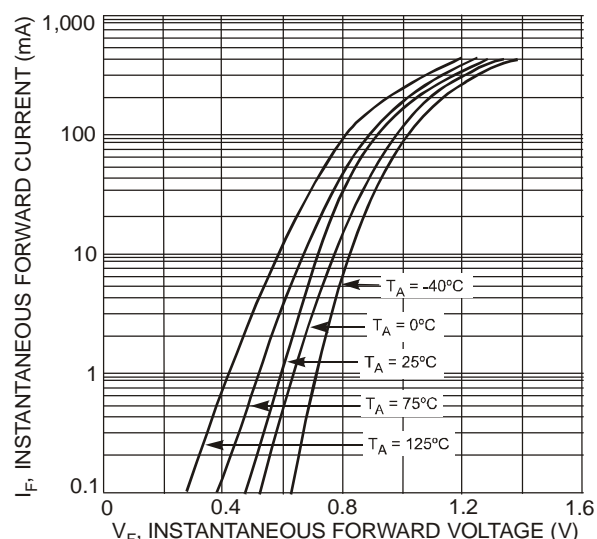


Fig. 2 Typical Forward Characteristics, Per Element

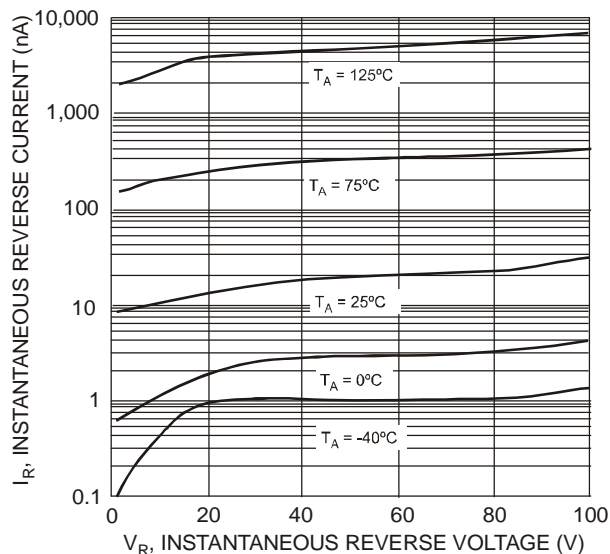


Fig. 3 Typical Reverse Characteristics, Per Element

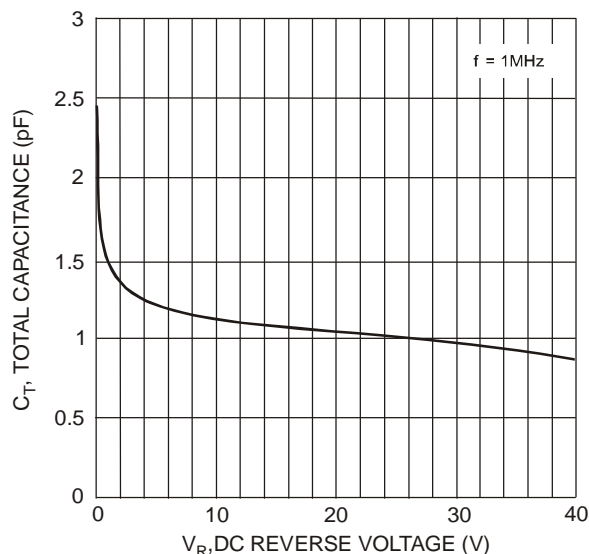
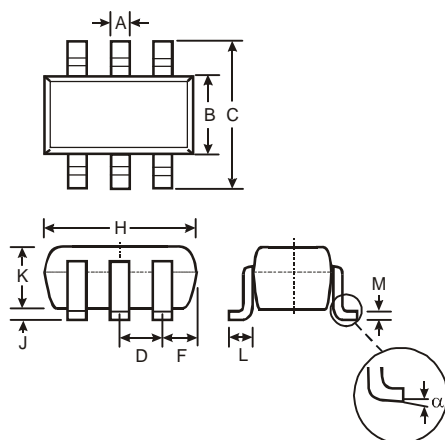


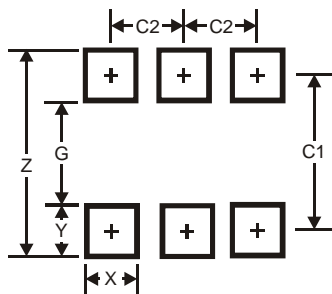
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

## Package Outline Dimensions



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
$\alpha$	0°	8°
All Dimensions in mm		

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

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